

ABSTRACT OF THE DISCLOSURE

An adhesive material is used for connecting a protuberant electrode of an electronic component to a terminal electrode of a circuit board for carrying said electronic component through the adhesive material containing at least one curable resin and inorganic particles. The adhesive material is characterized in that as to the inorganic particles, their specific surface area S (m^2/g) satisfies Equation (1) below, their mean particle size D_1 (μm) and maximum particle size D_2 (μm) respectively satisfy Equations (2) and (3) below,

$$3 < S \leq 17 \quad (1)$$

$$D_1 \leq 5 \quad (2)$$

$$D_2 \leq 0.5 (h_1 + h_2) \quad (3)$$

(wherein h_1 represents the height of the protuberant electrode in the electronic component, and h_2 represents the height of the terminal electrode in the circuit board), and the content of said inorganic particles is 10 to 60 vol %.